


Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32L4Q5RGT6P	725W*471XXXZ	A	998Z	19-05-2021
	Amount	UoM	Unit type	ST ECOPACK Grade
	363.67	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Tin (Sn), immersion	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	10x10x1.4	64	L Bend	
Comment	Package : 5W LQFP 64 10x10x1.4 1 0051434			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-25th June 2020				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	725W*471XXXZ				6000000.0	1000003.8
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die_ or dies	M-011 Other inorganic materials	17.589	mg	supplier	die	Silicon (Si)	7440-21-3		16.909	mg	961339	46495
				supplier	metallization	Aluminium (Al)	7429-90-5		0.033	mg	1876	91
				supplier	metallization	Copper (Cu)	7440-50-8		0.288	mg	16374	792
				supplier	metallization	Cobalt (Co)	7440-48-4		0.001	mg	57	3
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.093	mg	5287	256
				supplier	metallization	Titanium (Ti)	7440-32-6		0.003	mg	171	8
				supplier	metallization	Tungsten (W)	7440-33-7		0.002	mg	114	5
				supplier	Passivation	Silicon Nitride	12033-89-5		0.073	mg	4150	201
				supplier	Passivation	Silicon Oxide	7631-86-9		0.187	mg	10632	514
				supplier								
Glue epoxy_3230_henkel	M-011 Other inorganic materials	2.393	mg	Supplier	Metals	Silver	7440-22-4		1.950	mg	815000	5362
				Supplier	Plastics/polymers	2,2'-(Methylenebis(phenyleneoxymethylene))	39817-09-9		0.072	mg	30000	197
				Supplier	Organic Compounds	Dihydro-3-(tetrapropenyl)furan-2,5-dione	26544-38-7		0.072	mg	30000	197
				Supplier	Organic Compounds	Epoxy resin	Proprietary		0.072	mg	30000	197
				Supplier	Organic Compounds	Dodecylloxirane	3234-28-4		0.072	mg	30000	197
				Supplier	Organic Compounds	Hexahydromethylphthalic anhydride	25550-51-0		0.072	mg	30000	197
				Supplier	Organic Compounds	Epoxy resin modifier	Proprietary		0.072	mg	30000	197
				Supplier	Metallic compounds	Copper oxide	1317-38-0		0.012	mg	5000	33
				Supplier	Plastics/polymers	Epoxy Resin A	Trade Secret		5.000	mg	21000	13748
				Supplier	Plastics/polymers	Epoxy Resin B	Trade Secret		5.000	mg	21000	13748
Encapsulation_eme_g631shq_sumitor	M-011 Other inorganic materials	238.085	mg	Supplier	Plastics/polymers	Phenol Resin	Trade Secret		13.333	mg	56000	36662
				Supplier	Glass	Silica(Amorphous)A	60676-86-0		185.813	mg	780450	510944
				Supplier	Glass	Silica(Amorphous)B	7631-86-9		27.456	mg	115320	75498
				Supplier	Non-metals	Carbon Black	1333-86-4		1.483	mg	6230	4079
				Supplier	Metals	Gold	7440-57-5		0.864	mg	1000000	2375
Wire_Auha3_Heraeus	Bonding Wire	0.864	mg	Supplier	Metals	Tin	7440-31-5		1.438	mg	1000000	3954
Plating Anode_Pure Tin_Asahi	M-011 Other inorganic materials	1.438	mg	Supplier	Metals	Copper	7440-50-8		100.428	mg	972200	276155
Leadframe_C194+Ag_Mitsui	Copper & its alloys	103.300	mg	Supplier	Metals	Iron	7439-89-6		2.366	mg	22900	6505
				Supplier	Metals	Zinc	7440-66-6		0.155	mg	1500	426
				Supplier	Non-Metals	Phosphorus	7723-14-0		0.031	mg	300	85
				Supplier	Metals	Silver	7440-22-4		0.320	mg	3100	881